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## Contents

### 1 Simulation of the Sputtering Process

<i>T. Ono, T. Kenmotsu, and T. Muramoto</i> .....	1
1.1 Introduction .....	1
1.2 Computer Simulation Codes .....	2
1.3 Total Sputtering Yield .....	5
1.3.1 Incident-Energy Dependence of Sputtering Yield .....	5
1.3.2 Incident-Angle Dependence of Sputtering Yield .....	9
1.4 Differential Sputtering Yield .....	16
1.4.1 Energy Spectrum of Sputtered Atoms .....	16
1.4.2 Angular Distribution of Sputtered Atoms .....	21
1.5 Sputtering from Rough Surface .....	28
1.6 Sputtering of Compound Targets .....	30
1.7 Conclusion .....	37
References .....	39

### 2 Electron Emission from Surfaces Induced by Slow Ions and Atoms

<i>R.A. Baragiola and P. Riccardi</i> .....	43
2.1 Introduction .....	43
2.2 Physical Mechanisms .....	44
2.2.1 Excitation Mechanisms .....	44
2.2.2 Separation of PEE and KEE .....	46
2.2.3 Electron Transport and Escape into Vacuum .....	46
2.3 Electron Yields .....	46
2.3.1 Dependence of the Electron Yields on Ion Velocity .....	47
2.3.2 Electron Energy and Angular Distributions .....	48
2.3.3 Electron Emission from Contaminant Surface Layers .....	48
2.4 The Role of Ion-Induced Electron Emission in Glow Discharges ...	50
2.4.1 Effect of Electron Recapture at the Cathode .....	53
2.4.2 Effect of Changes in the Chemical Composition of the Cathode .....	56

2.5 Outlook .....	58
References .....	58
<b>3 Modeling of the Magnetron Discharge</b>	
<i>A. Bogaerts, I. Kolev, and G. Buyle</i> .....	61
3.1 Introduction .....	61
3.1.1 The Magnetic Field .....	62
3.1.2 The Magnetron Discharge .....	63
3.1.3 The Particle–Target Interaction .....	63
3.1.4 Particle Transport in the Gas Phase .....	64
3.1.5 Film Growth on the Substrate .....	64
3.2 Overview of Different Modeling Approaches for Magnetron Discharges .....	65
3.2.1 Analytical Models .....	66
3.2.2 Fluid Models .....	67
3.2.3 The Boltzmann Equation .....	68
3.2.4 Monte Carlo Simulations .....	69
3.2.5 Hybrid Models .....	71
3.2.6 PIC-MCC Simulations .....	72
3.3 Challenges Related to Magnetron Modeling .....	74
3.3.1 Secondary Electron Emission Yield ( $\gamma$ ) .....	75
3.3.2 Recapture .....	75
3.3.3 Electron Mobility .....	76
3.3.4 Modeling “Industrially Relevant” Magnetron Discharges ....	76
3.4 Two-Dimensional Semi-Analytical Model for a DC Planar Magnetron Discharge .....	78
3.4.1 Description of the Model .....	79
3.4.2 Examples of Calculation Results .....	81
3.5 PIC-MCC Model for a DC Planar Magnetron Discharge .....	83
3.5.1 Particle-In-Cell Model .....	83
3.5.2 Monte Carlo Collision Method .....	95
3.5.3 Methods for Speeding Up the Calculations .....	99
3.5.4 Examples of Calculation Results .....	103
3.6 Extension of the PIC-MCC Model: To Include Sputtering and Gas Heating .....	115
3.6.1 Description of the Model .....	116
3.6.2 Examples of Calculation Results .....	119
3.7 Conclusions and Outlook for Future Work .....	123
References .....	124
<b>4 Modelling of Reactive Sputtering Processes</b>	
<i>S. Berg, T. Nyberg, and T. Kubart</i> .....	131
4.1 Introduction .....	131
4.2 Basic Model for the Reactive Sputtering Process .....	133
4.3 Steady State Equations .....	136

4.4	Influence of Material Properties and Processing Conditions . . . . .	141
4.4.1	Reactivity . . . . .	141
4.4.2	Sputtering Yield . . . . .	141
4.4.3	Pumping Speed . . . . .	142
4.4.4	Target Size . . . . .	143
4.4.5	Mixed Targets . . . . .	143
4.4.6	Two Reactive Gases . . . . .	145
4.4.7	Reactive Co-Sputtering . . . . .	147
4.4.8	Comment on Pulsed DC Reactive Sputtering . . . . .	150
4.4.9	Secondary Electron Emission . . . . .	150
4.4.10	Ion Implantation . . . . .	150
4.5	Concluding Remarks . . . . .	151
	References . . . . .	151

## 5 Depositing Aluminium Oxide:

### A Case Study of Reactive Magnetron Sputtering

	<i>D. Depla, S. Mahieu, and R. De Gryse</i> . . . . .	153
5.1	Introduction . . . . .	153
5.2	Some Experiments . . . . .	154
5.2.1	A First Series of Experiments . . . . .	154
5.2.2	A Second Series of Experiments: Oxygen Exposure and Plasma Oxidation . . . . .	156
5.2.3	Stability Experiments . . . . .	164
5.2.4	First Conclusions Based on the Experiments . . . . .	166
5.3	An Extended Model for Reactive Magnetron Sputtering . . . . .	167
5.3.1	The Description of Reactive Ion Implantation During Sputtering . . . . .	167
5.3.2	The Influence of Chemisorption and Knock-On Effects . . . . .	171
5.3.3	Calculation of the Reactive Gas Partial Pressure as a Function of the Reactive Gas Flow . . . . .	173
5.4	Confrontation Between Experiment and Model . . . . .	175
5.4.1	Simultaneous Reactive Ion Implantation and Sputtering Without Chemical Reaction . . . . .	175
5.4.2	Simultaneous Reactive Ion Implantation and Sputtering with Chemical Reaction . . . . .	176
5.5	Towards a More Complete Model for Reactive Magnetron Sputtering . . . . .	186
5.5.1	Plasma-Related Topics . . . . .	186
5.5.2	Deposition Profiles and Erosion Profiles . . . . .	187
5.5.3	Rotating Magnetrons . . . . .	191
5.6	Conclusion . . . . .	193
	References . . . . .	196

## 6 Transport of Sputtered Particles Through the Gas Phase

<i>S. Mahieu, K. Van Aeken, and D. Depla</i> .....	199
6.1 Introduction .....	199
6.2 Radial Distribution Where Sputtered Particles Leave the Target .....	200
6.3 Energy and Angular Distribution of Sputtered Particles Leaving the Target .....	201
6.3.1 Sigmund–Thompson Theory for the Linear Cascade Regime .....	201
6.3.2 Other Analytical Models .....	204
6.3.3 Comparison to Experimental Results .....	206
6.3.4 Numerical Method .....	207
6.3.5 Conclusions .....	208
6.4 Describing the Collision with the Gas Particle .....	208
6.4.1 The Mean Free Path .....	210
6.4.2 The Scattering Angle .....	211
6.4.3 The Interaction Potential .....	213
6.5 Gas Rarefaction .....	217
6.6 Typical Results of a Binary Collision Monte Carlo Code .....	218
6.7 Specific Example: In-Plane Alignment of Biaxially Aligned Thin Films .....	223
6.8 Conclusions .....	224
References .....	225

## 7 Energy Deposition at the Substrate in a Magnetron Sputtering System

<i>S.D. Ekpe and S.K. Dew</i> .....	229
7.1 Introduction .....	229
7.2 Energy Measurement .....	231
7.3 Factors Affecting Energy Flux .....	232
7.3.1 Magnetron Power and Pressure .....	235
7.3.2 Substrate-Target Distance .....	235
7.3.3 Electrical Effects .....	236
7.4 Total Energy per Deposited Atom .....	237
7.5 Energy Model .....	239
7.5.1 Sputtered Particles .....	240
7.5.2 Reflected Neutrals .....	241
7.5.3 Plasma Radiation .....	242
7.5.4 Charge Carriers .....	243
7.5.5 Thermal Radiation .....	244
7.5.6 Model Results .....	246
7.6 Conclusions .....	251
References .....	251

**8 Process Diagnostics**

<i>J.W. Bradley and T. Welzel</i> .....	255
8.1 Introduction .....	255
8.2 Electrical Probes .....	256
8.2.1 Probe Techniques .....	257
8.2.2 Use of Electrical Probes in Pulsed Reactive Sputtering .....	258
8.3 Mass Spectrometry .....	270
8.3.1 Mass Spectrometry Technique .....	270
8.3.2 Application of Mass Spectrometry to Reactive Sputtering ..	271
8.4 Optical Emission Spectroscopy .....	286
8.4.1 Technique .....	286
8.4.2 Plasma Emission Monitoring .....	287
8.4.3 Time-Resolved OES in Pulsed Reactive Sputtering .....	288
8.5 Optical Imaging .....	292
8.6 Laser-Induced Fluorescence .....	293
8.7 Summary .....	296
References .....	296

**9 Optical Plasma Diagnostics****During Reactive Magnetron Sputtering**

<i>S. Konstantinidis, F. Gaboriau, M. Gaillard, M. Hecq, and A. Ricard</i> ..	301
9.1 Introduction .....	301
9.2 Emission Spectroscopy of Magnetron Plasmas .....	302
9.3 Resonant Absorption Spectroscopy of Magnetron Plasmas .....	311
9.4 Laser Spectroscopy of Magnetron Plasmas .....	320
9.4.1 Previous Works .....	320
9.4.2 Principle and Achievements .....	322
9.4.3 Application to Magnetron Discharges .....	326
9.5 Optical Diagnostic of High-Power Impulse Magnetron Sputtering Discharges .....	327
9.6 Conclusion .....	332
References .....	333

**10 Reactive Magnetron Sputtering****of Indium Tin Oxide Thin Films:****The Cross-Corner and Cross-Magnetron Effect**

<i>H. Kupfer and F. Richter</i> .....	337
10.1 Introduction .....	337
10.2 The CCE and CME as an Inhomogeneous Target Erosion .....	338
10.3 Evidence of the CCE and CME From In Situ Measurements .....	346
10.3.1 Introduction .....	346
10.3.2 The CCE and the Plasma Properties of Unipolar-Pulsed Single Magnetron Discharges .....	349
10.3.3 The CME and the Plasma Properties of Bipolar-Pulsed Dual Magnetron Discharges .....	350
10.3.4 The CME and the Thermal Load of the Substrates .....	353

## XII Contents

10.4 CCE, CME and Film Property Distribution: ITO as an Example . .	354
10.4.1 Introduction . . . . .	354
10.4.2 Unipolar DC-Pulsed Single Magnetron: CCE and ITO Film Properties . . . . .	356
10.4.3 Bipolar-Pulsed Dual Magnetron: CME and ITO Film Properties . . . . .	358
10.5 CCE, CME and the Role of the Atomic Oxygen in the Process Gas . . . . .	360
References . . . . .	365

### 11 Reactively Sputter-Deposited Solid Electrolytes and Their Applications

<i>P. Brionis, F. Lapostolle, and A. Billard</i> . . . . .	367
11.1 Introduction . . . . .	367
11.2 Crystallographic Basis of the Solid Electrolyte . . . . .	369
11.2.1 $O^{2-}$ Carriers . . . . .	369
11.2.2 $H^+$ Carriers . . . . .	374
11.2.3 $Na^+$ Carriers . . . . .	375
11.2.4 $Li^+$ Carriers . . . . .	377
11.2.5 Mixed Conductors . . . . .	377
11.3 Application of Solid Electrolytes . . . . .	377
11.3.1 Solid Oxide Fuel Cells . . . . .	377
11.3.2 Microbatteries . . . . .	392
11.3.3 Smart Windows . . . . .	399
11.4 Conclusion . . . . .	402
References . . . . .	404

### 12 Reactive Sputtered Wide-Bandgap p-Type Semiconducting Spinel $AB_2O_4$ and Delafossite $ABO_2$ Thin Films for “Transparent Electronics”

<i>A.N. Banerjee and K.K. Chattopadhyay</i> . . . . .	413
12.1 Introduction . . . . .	413
12.2 Spinel and Delafossite Material . . . . .	414
12.2.1 Spinel Materials . . . . .	414
12.2.2 Delafossite Materials . . . . .	416
12.3 p-Type Transparent Conducting Oxides Based on Spinel and Delafossite Structure . . . . .	417
12.3.1 Introduction to Transparent Conducting Oxides . . . . .	417
12.3.2 Transparent Electronics . . . . .	418
12.3.3 p-TCO with Spinel Structure . . . . .	420
12.3.4 p-TCO with Delafossite Structure . . . . .	422
12.3.5 Other Deposition Techniques: PLD, RF Sputter Deposition, Magnetron Sputtering with RTA, and Ion Exchange Method . . . . .	425
12.3.6 Reactive Sputtered p-TCO . . . . .	432

12.4	Transparent Junctions Based on Spinel and Delafossite Oxides . . . .	441
12.5	Origin of p-Type Conductivity in Wide-Bandgap Spinel and Delafossite Oxide Materials . . . . .	448
12.6	Reactive DC Sputter Deposition of Delafossite $\text{p-CuAlO}_{2+x}$ Thin Film . . . . .	455
12.6.1	Introduction . . . . .	455
12.6.2	Synthesis . . . . .	457
12.6.3	Results and Discussion . . . . .	458
12.7	Conclusions and Future Directions . . . . .	473
12.7.1	Conclusions . . . . .	473
12.7.2	Future Directions . . . . .	474
	References . . . . .	477
 <b>13 Oxide-Based Electrochromic Materials and Devices Prepared by Magnetron Sputtering</b>		
	<i>C.G. Granqvist</i> . . . . .	485
13.1	Introduction . . . . .	485
13.2	Energy Efficiency of Chromogenic Building Skins . . . . .	486
13.3	Electrochromic Device Design and Materials . . . . .	487
13.4	Properties and Applications of Electrochromic Foil . . . . .	490
13.5	Conclusion and Outlook . . . . .	493
	References . . . . .	494
 <b>14 Atomic Assembly of Magnetoresistive Multilayers</b>		
	<i>H. Wadley, X. Zhou, and W.H. Butler</i> . . . . .	497
14.1	Introduction . . . . .	497
14.1.1	Giant Magnetoresistance . . . . .	498
14.1.2	Atomic Scale Structure Effects . . . . .	501
14.1.3	Deposition and Growth Processes . . . . .	504
14.2	Atomistic Simulations . . . . .	505
14.2.1	Interatomic Potentials . . . . .	505
14.2.2	MD Model . . . . .	515
14.3	Growth of Metal Multilayers . . . . .	517
14.4	Ion-Assisted Growth of Metal Multilayers . . . . .	532
14.5	Dielectric Layer Deposition . . . . .	545
14.6	Ion-Assisted Reactive Growth of Dielectric Layers . . . . .	553
14.7	Conclusions . . . . .	555
	References . . . . .	555



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